

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Hsin-Heng Wang	03/08/2007
Chiu-Tsung Huang	03/08/2007
Shih-Siang Lin	03/08/2007
RECEIVING PARTY DATA	
Name:	Powerchip Semiconductor Corp.
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City:	Hsin-Chu City
State/Country:	TAIWAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	11686957
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NAME OF SUBMITTER:	WINSTON HSU
Total Attachments: 2 source=lksp0058usa0_a1_1_np005#page1.tif source=lksp0058usa0_a1_1_np005#page2.tif	

CH \$40.00 11686957

ASSIGNMENT OF INVENTION

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

ASSIGNOR(S) (Inventors):

Name: Hsin-Heng Wang Nationality: R.O.C.

Address: No.52, Sianjheng 18th St., Jhubei City, Hsinchu County, Taiwan, R.O.C.

Name: Chiu-Tsung Huang Nationality: R.O.C.

Address: No.37, Alley 1, Lane 30, Fucyun St., Hsinchu City, Taiwan, R.O.C.

Name: Shih-Siang Lin Nationality: R.O.C.

Address: 5F., No.111, Gueising Rd., Banciao City, Taipei County, Taiwan, R.O.C.

Hereby sells, assigns and transfers to

ASSIGNEE(S):

Name: Powerchip Semiconductor Corp.

Address: No. 12, Li-Hsin Rd. I, Science Park, Hsin-Chu City 300, Taiwan, R.O.C.

and the successors and assignees of the ASSIGNEE the entire right, title, and interest in and to any and all improvements which are disclosed in the invention entitled:

" IMAGE SENSOR AND FABRICATION METHOD THEREOF"

Which is found in :

- (a) + U.S. patent application executed on even date
- (b) _____ U.S. patent application executed on _____
- (c) _____ U.S. application serial no. _____
- (d) _____ patent no. _____ issued _____

and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WITNESS WHEREOF, We have hereunto set hand and seal this 3/8 '07 (Date of signing). (請發明人務必簽署上列日期。)

(Type name of inventor)

Signature of INVENTOR

Hsin-Heng Wang

Hsin-Heng Wang 3/8 '07

Chiu-Tsung Huang

Chiu-Tsung Huang 3/8 '07

Shih-Siang Lin

Shih Siang Lin 3/8 '07